

EMERGENCY PHONE 1-800-255-3924

TECHNICAL DATA SHEETS

MP 5405 FLEX

Description:

MP 5405 FLEX is a two part unfilled rubber modified epoxy adhesive designed for high speed bonding of metals, ceramics, and most plastics. It cures to a tough semi-rigid material, and is free flowing in viscosity. It gives good resistance to water, salt spray, inorganic acids and bases, and most organic solvents. It was especially formulated to a 1:1 mix ratio for use in either MMD equipment or side-by-side dual cartridges for easy dispensing.

A handling cure is normally achieved at room temperature within 20 - 30 minutes with full cure in 24 hours. An elevated temperature cure schedule can be used to reach final properties quickly.

Handling and Storage:

- 1) Bring both components to room temperature prior to mixing. Mix 1 parts A to 1 part B thoroughly.
- 2) Allow to cure undisturbed until product is fully gelled or tack-free to the touch.
- 3) Clean up uncured resin with suitable organic solvent such as MEK, acetone or a chlorinated solvent.

Mix Ratio:

1A:1B by weight or 1A:1B by volume.

Shelf Life:

12 Months

Handling Characteristics:

All properties given are at 25C unless otherwise noted.

Color	Clear	
Viscosity	Part A	7,000 cps
	Part B	15,000 cps
	Mixed	11,000 cps
Specific Gravity	Part A	1.11
	Part B	1.15
	Mixed	1.13
Pot Life	3 - 5 minutes	
Mass	20 grams	
Tensile Strength	2300 psi	
Lap Shear (Al to Al)		
Tensile Elongation	5 - 10%	
Tensile Strength	6500 psi	
Temperature Range	-40 to 130C	
Hardness	58	
Method	Shore -D	
Linear Coefficient of Thermal Expansion	(x 10 ⁶)/C	62
Dielectric Constant	4.5	
(25C, 100Hz)		
Dielectric Strength	410 v/mil	
Volume Resistivity	8 x 10 ¹⁴ ohm-cm	

Engineering Excellence

For technical information
and support call **1-800-552-0299** or visit our website at

www.instantca.com